This user’s guide describes the characteristics, operation, and use of the BUF08821EVM-USB evaluation board. It discusses how to set up and configure the software and hardware, and reviews various aspects of the program operation. Throughout this document, the terms evaluation board, evaluation module, and EVM are synonymous with the BUF08821EVM-USB. This document also includes information regarding operating procedures and input/output connections, an electrical schematic, printed circuit board (PCB) layout drawings, and a parts list for the EVM.

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1 Overview

The BUF08821 is a programmable gamma-voltage generator and \( V_{\text{COM}} \) calibrator. This device offers two banks of eight programmable gamma channels and one programmable \( V_{\text{COM}} \) channel, making it ideal for 10-bit source TFT-LCD reference drivers. The BUF08821EVM-USB is a platform for evaluating the performance of the BUF08821 under various signal, reference, and supply conditions. This document gives a general overview of the BUF08821EVM-USB, and provides a general description of the features and functions to be considered while using this evaluation module.

1.1 BUF08821EVM-USB Kit Contents

Table 1 summarizes the contents of the BUF08821EVM-USB kit. Contact the Texas Instruments Product Information Center nearest you if any component is missing. It is highly recommended that you also check the BUF08821 product folder on the TI web site at www.ti.com to verify that you have the latest versions of the related software.

<table>
<thead>
<tr>
<th>Item</th>
<th>Quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td>BUF08821 PCB Test Board</td>
<td>1</td>
</tr>
<tr>
<td>USB_DIG_Platform PCB</td>
<td>1</td>
</tr>
<tr>
<td>USB Cable</td>
<td>1</td>
</tr>
<tr>
<td>Barrel plug cable assembly (part # 10-01935 - Tensility International Corporation) for external power supply</td>
<td>1</td>
</tr>
<tr>
<td>User’s Guide CD-ROM</td>
<td>1</td>
</tr>
</tbody>
</table>

1.2 Related Documentation from Texas Instruments

The following documents provide information regarding Texas Instruments' integrated circuits used in the assembly of the BUF08821EVM-USB. This user’s guide is available from the TI web site under literature number SBOU095. Any letter appended to the literature number corresponds to the document revision that is current at the time of the writing of this document. Newer revisions may be available from the TI web site, or call the Texas Instruments’ Literature Response Center at (800) 477-8924 or the Product Information Center at (972) 644-5580. When ordering, identify the document by both title and literature number.

<table>
<thead>
<tr>
<th>Related Documentation</th>
</tr>
</thead>
<tbody>
<tr>
<td>Document</td>
</tr>
<tr>
<td>BUF08821 Product Data Sheet</td>
</tr>
<tr>
<td>USB_DIG_Platform User Guide</td>
</tr>
</tbody>
</table>
2 BUF08821EVM-USB Hardware Setup

Figure 1 shows the system setup for the BUF08821EVM-USB. The PC runs software that communicates with the USB_DIG_Platform. The USB_DIG_Platform generates the analog and digital signals used to communicate with the BUF08821. Connectors on the BUF08821 allow the user to connect to the device under test (DUT), in order to monitor the power, current, and voltage of the DUT.

![Figure 1. BUF08821EVM-USB Hardware Setup](image)

2.1 Theory of Operation for BUF08821 Hardware

A block diagram of the BUF08821 test board hardware setup is shown in Figure 2. The functionality of the PCB is such that it provides connections to the I²C interface and general-purpose inputs/outputs (GPIOs) on the USB_DIG_Platform board. It also provides connection points for external connections of the shunt voltage, bus voltage, and ground.

![Figure 2. BUF08821EVM-USB Board Block Diagram](image)
### 2.2 Signal Definitions of J1 (25-Pin Male DSUB)

Table 2 lists the different signals connected to J1 on the BUF08821EVM-USB test board.

**Table 2. Signal Definition of J1 (25-Pin Male DSUB) on BUF08821EVM-USB Board**

<table>
<thead>
<tr>
<th>PIN on J1</th>
<th>Signal</th>
<th>BUF08821 Pin</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>2</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>3</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>4</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>5</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>6</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>7</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>8</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>9</td>
<td>I2C_SCK</td>
<td>No connection</td>
</tr>
<tr>
<td>10</td>
<td>I2C_SDA2</td>
<td>No connection</td>
</tr>
<tr>
<td>11</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>12</td>
<td>I2C_SCK_ISO</td>
<td>I2C clock signal (SCL) channel 1; can be disconnected using a switch</td>
</tr>
<tr>
<td>13</td>
<td>I2C_SDA_ISO</td>
<td>I2C data signal (SDA) channel 1; can be disconnected using a switch</td>
</tr>
<tr>
<td>14</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>15</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>16</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>17</td>
<td>V_{OUT}</td>
<td>Switched 3V/5V power. Note that when power is switched off, digital I/O is also switched off.</td>
</tr>
<tr>
<td>18</td>
<td>V_{CC}</td>
<td>No connection</td>
</tr>
<tr>
<td>19</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>20</td>
<td>N/C</td>
<td>No connection</td>
</tr>
<tr>
<td>21</td>
<td>GND</td>
<td>Common ground connection</td>
</tr>
<tr>
<td>22</td>
<td>SPI_SCK</td>
<td>No connection</td>
</tr>
<tr>
<td>23</td>
<td>SPI_CS1</td>
<td>No connection</td>
</tr>
<tr>
<td>24</td>
<td>SPI_DOUT1</td>
<td>No connection</td>
</tr>
<tr>
<td>25</td>
<td>SPI_DIN1</td>
<td>No connection</td>
</tr>
</tbody>
</table>
2.2.1 Theory of Operation for USB_DIG_Platform

Figure 3 shows the block diagram for the USB_DIG_Platform. This platform is a general-purpose data acquisition system that is used on several different Texas Instruments evaluation modules. The details of its operation are included in a separate document, SBOU058 (available for download at www.ti.com). The block diagram shown in Figure 3 gives a brief overview of the platform. The primary control device on the USB_DIG_Platform is the TUSB3210.

![Figure 3. USB_DIG_Platform Block Diagram](image)

3 BUF08821EVM-USB Hardware Overview

The BUF08821EVM-USB hardware overview involves connecting the two PCBs of the EVM together, applying power, connecting the USB cable, and setting the jumpers. This section presents the details of this procedure.

3.1 Electrostatic Discharge Warning

CAUTION

Many of the components on the BUF08821EVM-USB are susceptible to damage by electrostatic discharge (ESD). Customers are advised to observe proper ESD handling precautions when unpacking and handling the EVM, including the use of a grounded wrist strap at an approved ESD workstation.
3.2 Typical Hardware Connections

To set up the BUF08821EVM-USB hardware, connect the two PCBs of the EVM together, and apply a power source to the BUF08821EVM-USB test board. The external connections may be the real-world system that the BUF08821 will be incorporated into. Figure 4 illustrates the typical hardware connections.
3.3 Connecting the Hardware

To connect the two PCBs of the BUF08821EVM-USB together, gently push on both sides of the DSUB connectors (as shown in Figure 5). Note that the USB_Dig_Platform board has two DSUB connectors; either may be used. Make sure that the two connectors are completely pushed together; loose connections may cause intermittent operation.

3.4 Connecting Power

After the two parts of the BUF08821EVM-USB are conjoined, connect a +9V wall supply to the USB_Dig_Platform board, as Figure 5 shows. Always connect power before connecting the USB cable. If you connect the USB cable before connecting the power, the computer will attempt to communicate with an unpowered device that will not be able to respond.

In addition, the BUF08821EVM-USB also requires an external power source. This source is not included with the kit. Its voltage may differ depending on your testing needs, and it will be connected to the terminal T1.

![Figure 5. Connecting External Power to the EVM](image-url)
3.5 Connecting the USB Cable to the BUF08821EVM

Once power is connected, the USB cable must be connected to the USB_DIG_Platform, as shown in Figure 6. Note that the BUF08821EVM-USB test board and the USB_DIG_Platform board must each be powered on before connecting the USB cable. Typically, the computer will respond with a Found New Hardware, USB Device pop-up dialog. The pop-up window typically changes to Found New Hardware, USB Human Interface Device. This pop-up indicates that the device is ready to be used. The USB_DIG_Platform uses the human interface device drivers that are part of the Microsoft® Windows® operating system.

In some cases, the Windows Add Hardware Wizard may pop up. If this prompt appears, allow the system device manager to install the human interface drivers by clicking Yes when requested to install drivers. Windows will confirm installation of the drivers with the message shown in Figure 7.
3.6 BUF08821EVM-USB Default Jumper Settings

Figure 8 shows the default jumpers configuration for the BUF08821EVM-USB. In general, the jumper settings of the USB_DIG_Platform will not need to be changed. You may want to change some of the jumpers on the BUF08821EVM-USB board to match your specific configuration. For instance, you may wish to set a specific I2C address on the DUT.

![Figure 8. BUF08821EVM-USB Default Jumper Settings](image)

Jumpers 1 through 5 on the BUF08821EVM-USB are all typically set to the same position. When set to the INT position, the signals from the digital supply, bank select, and the digital communication lines are generated and controlled from the USB_DIG_Platform or by the onboard bank select switch. When these jumpers are set to the EXT position, the previously described signals connect to the terminal strips T2, T3, and T4. Jumper 5 controls the I2C address pin for the BUF08821. This jumper can set the address for A0 to either high or low.
Table 3 summarizes the function of the BUF08821EVM-USB board jumpers. For most application, Jumpers 1 through 5 are all set to the default positions.

### Table 3. BUF08821EVM-USB Test Board Jumper Functions

<table>
<thead>
<tr>
<th>Jumper</th>
<th>Default</th>
<th>Purpose</th>
</tr>
</thead>
<tbody>
<tr>
<td>JMP1</td>
<td></td>
<td>This jumper selects whether the SCL pin on the BUF08821 is connected to the I2C_SCK_ISO signal generated from the USB_DIG_Platform or whether the SCL pin is connected to terminal T4, allowing for an external source to control the I(^2)C clock line. The default INT position connects the SCL pin to the I2C_SCK_ISO control signal.</td>
</tr>
<tr>
<td>JMP2</td>
<td></td>
<td>This jumper selects whether the VSD pin on the BUF08821 is connected to the V(<em>{DUT}) signal generated from the USB_DIG_Platform or whether the digital supply pin is connected to terminal T2, allowing for an external supply to power the digital circuitry. The default INT position connects the VSD pin to the V(</em>{DUT}) control signal.</td>
</tr>
<tr>
<td>JMP3</td>
<td></td>
<td>This jumper selects whether the BKSEL pin on the BUF08821 is controlled by the manual switch located on the BUF08821EVM-USB or whether the BKSEL can be controlled by an external source connected to terminal T3. The default INT position allows the BKSEL pin to be controlled by the manual switch.</td>
</tr>
<tr>
<td>JMP4</td>
<td></td>
<td>This jumper selects whether the SDA pin on the BUF08821 is connected to the I2C_SDA_ISO signal generated from the USB_DIG_Platform or whether the SDA pin is connected to terminal T4, allowing for an external source to control the I(^2)C data line. The default INT position connects the SDA pin to the I2C_SDA_ISO control signal.</td>
</tr>
<tr>
<td>JMP5</td>
<td></td>
<td>This jumper sets the I(^2)C A0 address selection. Two separate I(^2)C addresses can be selected, depending upon whether JMP1 is set to high or low.</td>
</tr>
</tbody>
</table>
Table 4 summarizes the function of the USB_DIG_Platform jumpers. For most applications, the default jumper position should be used. A separate document (SBOU058) gives details regarding the operation and design of the USB_DIG_Platform.

Table 4. USB_DIG_Platform Jumper Functions

<table>
<thead>
<tr>
<th>Jumper</th>
<th>Default</th>
<th>Purpose</th>
</tr>
</thead>
<tbody>
<tr>
<td>JUMP1</td>
<td>EXT</td>
<td>This jumper selects external power or bus power. External power is applied on J5 or T3 (9V dc). Bus power is 5V from the USB bus. External power is typically used because the USB Bus power is noisy.</td>
</tr>
<tr>
<td>JUMP2</td>
<td>EXT</td>
<td>Same as JUMP1.</td>
</tr>
<tr>
<td>JUMP3</td>
<td>EE ON</td>
<td>This jumper determines where the TUSB3210 will load the USB_DIG_Platform firmware upon power-up or reset. The EE Off position is used for development for development or firmware update.</td>
</tr>
<tr>
<td>JUMP4, JUMP5</td>
<td>L, L</td>
<td>This jumper sets the address for the USB board. The only reason to change from the default setting is if multiple boards are being used.</td>
</tr>
<tr>
<td>JUMP9</td>
<td>5V</td>
<td>This jumper selects the voltage of the device under test supply (V_{DUT} = 5V or 3V). This jumper is typically the only jumper that is changed for most applications.</td>
</tr>
<tr>
<td>JUMP10</td>
<td>WP ON</td>
<td>This write protects the firmware EEPROM.</td>
</tr>
<tr>
<td>JUMP11</td>
<td>WP ON</td>
<td>This write protects the calibration EEPROM.</td>
</tr>
<tr>
<td>JUMP13</td>
<td>REG</td>
<td>Uses the regulator output to generate the V_{DUT} supply. The USB bus can be used as the V_{DUT} supply.</td>
</tr>
<tr>
<td>JUMP14</td>
<td>9V</td>
<td>Uses the external power (9V as opposed to the bus)</td>
</tr>
<tr>
<td>JUMP17</td>
<td>BUS</td>
<td>While in the BUS position V_{DUT} operation is normal. While in the V_{RAW} position the V_{DUT} supply is connected to an external source. This configuration allows for any value of V_{DUT} between 3V and 5V. (1)</td>
</tr>
<tr>
<td>JUMP18</td>
<td>V_{DUT}</td>
<td>Connects the pull-up on GPIO to the V_{DUT} supply or the V_{CC} supply.</td>
</tr>
</tbody>
</table>

(1) CAUTION: Adjusting outside of this range will damage the EVM.

3.7 BUF08821EVM-USB Features

This section describes some of the hardware features present on the BUF08821EVM-USB board.

3.7.1 BKSEL: OTP Bank Selection Switch

The BKSEL switch located on the BUF08821EVM-USB board selects the memory bank to be used when operating the EVM. Bank 0 selects the gamma curve that is stored in Bank_0 of the BUF08821. Bank 1 selects the gamma curve that is stored in Bank_1 of the BUF08821. This switch also determines the OTP bank that is written to by the BUF08821EVM-USB software. Note that this switch is not active if JMP3 is set to EXT.

3.7.2 JMP1: I2C SCK Control Setting

Jumper JMP1 selects where the BUF08821 I2C SCL pin is connected. If JMP1 is set in the INT position, the I2C clock signal is generated from the I2C_SCK_ISO signal from the USB_DIG_Platform.

When JMP1 is set in the EXT position, an external source connected to SCL pin of terminal T4 can be used to provide the I2C SCK signal for the BUF08821.
3.7.3 JMP2: VSD Control Setting

Jumper JMP2 selects where the BUF08821 digital supply pin is connected. If JMP2 is set in the INT position, the V_{SD} pin is connected to the switchable V_{DUT} signal generated from the USB_DIG_Platform. This voltage can be set to either 3.3V or 5V, depending on how JUMP9 on the USB_DIG_Platform is set. While JMP2 is set to the INT position, the V_{SD} Power button on the BUF08821 software is able to control whether the V_{DUT} supply voltage is turned on or off.

When JMP2 is set in the EXT position, an external supply connected to terminal T2 can be used to provide the digital supply voltage for the BUF08821.

3.7.4 JMP3: BKSEL Control Setting

Jumper JMP3 determines how the OTP memory bank selection is controlled. There are two settings for JMP3. The INT position specifies that control of the BKSEL pin is handled on the BUF08821EVM-USB board by the BKSEL switch. The EXT position for JMP3 allows for an external control signal connected to terminal T3 to determine the selection of which OTP bank to be used.

3.7.5 JMP4: I^{2}C SDA Control Setting

Jumper JMP4 selects where the BUF08821 I^{2}C SDA pin is connected. If JMP4 is set in the INT position, the I^{2}C data signal is generated from the I^{2}C_SDA_ISO signal from the USB_DIG_Platform. When JMP4 is set in the EXT position, an external source connected to SDA pin of terminal T4 can be used to provide the I^{2}C SDA signal for the BUF08821.

3.7.6 JMP5: I^{2}C Address Hardware Setting

Jumper JMP5 is used to set the hardware setting for the A0 I^{2}C address pin on the BUF08821. Using JMP5, the A0 address can be set to either logic '1' or logic '0' to allow for two unique I^{2}C addresses. See Section 5.2.1xx on how to configure the BUF08821EVM-USB software to match the JMP1 hardware setting.

3.7.7 BUF08821 Device Placement

The BUF08821EVM-USB offers the user two separate locations on the PCB where the BUF08821 test device can be installed. Location U2 allows for a BUF08821 device that is soldered down on a DIP adaptor board to be installed on the BUF08821EVM-USB. The output capability of the BUF08821 device that is soldered on this adaptor board can be fully evaluated. The PowerPAD™ of this soldered BUF08821 is connected correctly, allowing the device to dissipate the necessary power while being evaluated.

The U1 location on the BUF08821EVM-USB is a 20-pin test socket that allows the user to evaluate and program many devices very quickly. One drawback to this socket is that there is no connection to the PowerPAD of the BUF08821. Because of this limitation, while in this socket, the BUF08821 device cannot operate at its full output capability as a result of thermal dissipation restrictions.

CAUTION

Only one location should be populated at a time. The use of both locations simultaneously will damage one or both of the devices being tested.

3.7.8 Terminal Strip TPG1

Terminal strip TPG1 provides the individual output signals on a single row of headers as well as a row of test points. This footprint provides the user with multiple options regarding how to interface the output signals of the BUF08821 with the available display panel. Users can develop a custom cable to connect the headers to their respective panels directly, or to solder directly to the individual test points.
4 BUF08821EVM-USB Software

4.1 Hardware Requirements

The BUF08821EVM-USB software has been tested on Microsoft® Windows® XP, Vista, and Windows 7 operating systems (OS) with United States and European regional settings.

4.2 Software Installation

The BUF08821EVM-USB software is included on the CD that is shipped with the EVM kit. It is also available through the BUF08821EVM product folder on the TI web site. To install the software to a computer, insert the disc into an available CD-ROM drive. Navigate to the drive contents and open the BUF08821EVM software folder. Locate the compressed file (BUF08821EVM.zip) and open it using WinZIP® or a similar file compression program; extract the BUF08821EVM files into a specific BUF08821EVM folder (for example, C:\BUF08821EVM) on your hard drive.

Once the files are extracted, navigate to the BUF08821EVM folder you created on the hard driver. Locate the setup.exe file and execute it to start the installation, as shown in Figure 9.

![Figure 9. BUF08821EVM-USB Software Installation](image)

After the installation process initializes, the user is given the choice of selecting the directory in which to install the program; the default location is C:\Program Files\BUF08821\ and C:\Program Files\National Instruments\ as shown in Figure 9. Following this option, two license agreements are presented that must be accepted, as shown in Figure 10. After accepting the Texas Instruments and National Instruments license agreements, the progress bar opens and shows the installation of the software, as Figure 11 illustrates. Once the installation process is completed, click Finish.
Figure 10. BUF08821EVM-USB License Agreements

Figure 11. BUF08821EVM-USB Software Installation Progress
4.3 Software Description and Set-Up

The BUF08821EVM-USB software allows the user to read and write to all registers in the BUF08821 gamma correction buffer. Furthermore, it allows programming of the OTP register on the BUF08821. The software also permits the user to select either I²C address. Press the About button, as shown in Figure 12, to verify that you have the latest version of the software.

The EVM software is controlled through a graphical user interface (GUI). The software communicates with the EVM through an available COM or other serial port on the PC. Pressing the COM Setting button brings up a panel that allows you to change the serial port number through which the PC communicates with the BUF08821EVM, as shown in Figure 12. COM1 is an appropriate choice for most PCs. You can also set the appropriate baud rate through the same dialog box.

Figure 12. BUF08821EVM-USB Software About Button

5 BUF08821EVM-USB Software Overview

This section discusses how to use the BUF08821EVM-USB software.

5.1 Starting the BUF08821EVM-USB Software

The BUF08821 software can be operated through the Windows Start menu. From Start, select All Programs; then select the BUF08821EVM program.

Figure 13 shows an error that pops up if the computer cannot communicate with the EVM. If you receive this error, first check to see that the USB cable is properly connected on both ends. This error can also occur if you connect the USB cable before the USB_DIG_Platform power source. Another possible source for this error is a problem with your PC USB Human Interface Device driver. Make sure that the device is recognized when the USB cable is plugged in; recognition is indicated by a Windows-generated confirmation sound.

Figure 13. BUF08821EVM-USB Software: Communication Error with the USB_DIG_Platform
5.2 Using the BUF08821 Software

5.2.1 I²C Address Selection

As mentioned previously in the BUF08821EVM-USB Features section (see Section 3.7), jumper JMP5 is used to set the I²C address pin of the BUF08821. Figure 14 shows how the hardware and software must both be set to allow for communication between the BUF08821EVM-USB and the software. Without jumper JMP5 and the software address button configured correctly, the software will not be able to communicate with the BUF08821 device.

![Figure 14. JMP5 Setting For Logic '0']

5.2.2 Measuring the Power Supply

You must measure the power supply \( (V_{\text{SUP}}) \) with respect to the GND on the BUF08821EVM-USB board and enter it in the \( V_{\text{SUP}} \) field located in the top section of the software interface, as shown in Figure 15.

![Figure 15. Measuring and Entering Power-Supply Voltage]

The voltages calculated for each channel are based on the value entered as \( V_{\text{SUP}} \), as shown in Equation 1. Note that \( \text{Code} \) is the value found in the channel registry converted to a decimal value.

\[
V_{\text{CHANNEL}} = \frac{V_{\text{SUP}} \times \text{Code}}{1024}
\]  

(1)

5.2.3 Read DAC Button

By pressing the Read DAC button in the BUF08821EVM-USB software, all of the BUF08821 DAC/V\( _{\text{COM}} \) registers are read to obtain the respective current register contents. Once the read procedure is complete, all of the corresponding text boxes are updated to show the current values present in the DAC/V\( _{\text{COM}} \) registers.
5.2.4 Write DAC Button

The method used to write the values in the DAC/V<sub>COM</sub> registers is based on whether or not the Auto Write feature is enabled. The BUF08821 has two methods of writing information into the DAC/V<sub>COM</sub> registers. The first method allows for the output voltage to change immediately after the writing to the DAC register. In the BUF08821EVM-USB software, this mode is configured by enabling the Auto Write feature found in the Buffer Menu dropdown menu. In this mode, as an individual channel is written to, the output voltage changes as soon as the user moves to a different text box in the software. The second method of writing to the DAC/V<sub>COM</sub> registers allows for the user to write multiple channels and then have all of the output voltages change at the same time, rather than each channel voltage changing as soon as it is written to.

Disabling the Auto Write feature in the software allows the user to enter all of the values desired for all of the channels and then press the Write DAC button to change all of the output voltage of all of the channels at one time. When the Auto Write feature is enabled, no change occurs to the output voltages when the Write DAC button is pressed. No change occurs because after the text box for a given channel has been updated, as soon as another item in the software is clicked, the Auto Write feature automatically performs a write command to the updated channel that then updates the output voltage. When in the Auto Write enabled mode, the Write DAC button cannot be pressed with different data in the corresponding channel text boxes than the values already stored in the DAC/V<sub>COM</sub> register; thus, no change occurs. Figure 16 shows the location in the Buffer Menu showing the Auto Write feature enabled. Clicking on the Auto Write feature again enables/disables the feature, depending on its current state.

![Figure 16. Auto Write Feature Enabled](image)

5.2.5 Reset Button

Pressing the Reset button in the BUF08821EVM-USB software performs two functions. The first function is to call a General-Call Reset for the BUF08821. The status of the DAC/V<sub>COM</sub> registers after this General-Call Reset has been called depends upon whether the OTP has been programmed or not. If the OTP has been programmed, the channel registers will be loaded with the last values programmed into the OTP memory. If the OTP memory has not been programmed, the channel registers will default to 1000000000, or mid-supply. The second function performed after the Reset button is pressed is that a Read DAC call is made to update the corresponding channel text boxes to the current value for each channel.
5.2.6 Save to File Button

The register configurations of the BUF08821 DACs are displayed in both analog voltage and in hexadecimal. The DAC codes (that is, gamma voltages) can be saved into a text file using the **Save to File** button.

Pressing the **Save to File** button opens a file-save dialog box similar to that shown in Figure 17. Pressing the folder icon creates a new folder on your PC. It is a good idea to create a directory exclusively for BUF08821 DAC code (that is, gamma voltage) files. Enter a unique file name in the *File name* field to store your BUF08821 register information. Press the **OK** button to save the file.

Saved BUF08821 DAC codes (gamma voltages) exist in a text file that can be opened in a text editor, as Figure 18 illustrates.
5.2.7 Load From File Button

The BUF08821EVM-USB software is also able to load data saved from previous evaluations. A saved register configuration can be loaded into the BUF08821 using the **Load From File** button, as shown in Figure 19. The program remembers where you saved the last register configuration. Simply select the desired configuration and press **Open**.

![Figure 19. Load From File Button and Window](image)

5.2.8 Changing the DAC/V<sub>COM</sub> Analog Voltage

The voltage of any of the DAC or V<sub>COM</sub> channels can be adjusted in several ways. First, you can change the voltage by entering the desired voltage directly in the voltage text box. In order to be able to manually type the voltage into the text box, you must first click on the cell to be edited. Click a second time and the cell turns from blue to black, and allows the user to type the updated voltage in the cell. The hexadecimal DAC codes can be entered in the **Code** column in the same manner.

Another method of changing the voltage of a DAC or V<sub>COM</sub> channel is through the use of the slider on the main software window. There is only a single slider that is used for all channels. In order to use the slider to adjust the voltage of a particular channel, that channel must first be selected. To select a channel, click on either the channel number, voltage, or code of a particular channel. The entire channel row highlights in blue to show the user that the channel is selected. Adjusting the slider bar then only updates the highlighted channel.

The final method to change DAC/V<sub>COM</sub> voltages is through the **±1 Code** and **±5 Code** buttons on the main software window. These buttons allow for fine and coarse adjustments, respectively, to the highlighted channel, giving the user the ability to quickly step the channel output up or down as needed without having to manually enter the changes in the **Code** column.
5.2.9 Run Batch Button

The Run Batch button (as highlighted in Figure 20) enables the user to configure the BUF08821 to cycle through different register configurations in a continuous loop. When connected to the end application, this feature can be used to cycle through different gamma settings to determine what the optimal settings must be for a given application.

When the Run Batch button is pressed, a new dialog box displays as Figure 20 shows. The delay time is the amount of time allowed between loading new configurations into the BUF08821 DUT.

Use the Single Step Up and Single Step Down buttons to step through the selected files manually. The currently-selected file name is displayed in the lower left corner area of the dialog box. Double-click on the file names to select them. Once a series of filenames have been selected, the check box turns dark. Double-click on a filename again to unselect it from the batch run.

![Figure 20. Run Batch Dialog Button and Window](image)
5.2.10 Control Panel Button

Pressing the Control Panel button brings up a display panel that allows you to adjust each channel using a set of graphical sliders, as shown in Figure 21. Simply drag the slider to adjust the desired channel output. The DAC code and corresponding output value of each channel change automatically. This function is similar to the slider present on the primary BUF08821EVM-USB software window that changes based on the channel that highlighted (as discussed in the above section).

![Figure 21. Control Panel Button and Window](image-url)
6 BUF08821EVM-USB Documentation

This section contains the complete bill of materials and schematic diagram for the BUF08821EVM-USB. Documentation information for the USB_DIG_Platform can be found in the USB_DIG_Platform User’s Guide, SBOU058, available at the TI web site at http://www.ti.com.

6.1 Schematic

Figure 22 shows the schematic for the BUF08821EVM-USB.

Figure 22. BUF08821EVM-USB Schematic
6.2 PCB Layouts

Figure 23 shows the PCB component layout of the BUF08821EVM-USB.

Figure 23. BUF08821EVM-USB PCB Top Layer (Component Side)
6.3 Bill of Materials

Table 5 lists the bill of materials for this EVM.

<table>
<thead>
<tr>
<th>Count</th>
<th>Value</th>
<th>RefDes</th>
<th>Description</th>
<th>Part Number</th>
<th>Mfr</th>
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<td>249kΩ</td>
<td>R1</td>
<td>Resistor, 249kΩ 1/16W .5% 0603 SMD</td>
<td>RR0816P-2493-D-39D</td>
<td>Susumu Co Ltd</td>
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<td>C1, C2</td>
<td>Capacitor, Tantalum 4.7μF 35V 10% SMD</td>
<td>293D475X9035C2TE3</td>
<td>Vishay/Sprague</td>
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<td>C5-C12</td>
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<td>C0603C104Z3VACTU</td>
<td>Kemet</td>
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<td>ENPLAS</td>
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<td>U2</td>
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<td>SS-110-G-2</td>
<td>Samtec</td>
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<td>SN74LVC1G17DBVR</td>
<td>Texas Instruments</td>
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<td>J1</td>
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<td>AMP/Tyco Electronics</td>
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<td>Samtec</td>
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<td>Samtec</td>
</tr>
</tbody>
</table>

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Original (March 2011) to A Revision

• Changed power supply in the BUF08821EVM-USB Kit Contents section. ......................................................... 2
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- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

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   will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in
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   order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s),
   excluding any postage or packaging costs.

10. **Governing Law:** These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas,
    without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to
    these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas.
    Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief
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